

HLT3500LV Thermal Conductive Gel

BENEFITS AND FEATURES

- Low volatile
- Easy to dispense and re-work
- High compressibility with low stress, good to stress-sensitive devices
- Long-term reliability
- Less oil separation
- No pump out and cracking
- Consumer electronics
- Telecommunications equipment
- Automotive electronics
- Memory
- Power modules

OVERVIEW

Honeywell HLT3500LV is two-part, dispensable thermal gel. It offers long-term reliability and superior softness to applications. The enhanced bonding force between the polymer base and the filler largely reduces the risk of oil separation during storage. Prior to curing, this material maintains good thixotropy so it maintains its shape well after dispensing easily dispensed. At the same time, viscosity of HLT3500LV is low and it is good for dispensing process.

Curing speed of HLT3500LV can be speeded up with heat.

STORAGE & USE

- Shelf life 6 months at 0-35°C, $\leq 65\%RH$

TYPICAL PROPERTIES

Property		HLT3500LV	Test Method
Color		Part A: White; Part B: Red	Visual
Mix Ratio		1:1	by Volume
Thermal Conductivity (W/m-K)		3.5	ASTM D5470
Thermal Impedance (°C-in ² /W) (1mm@10psi, Typical Value)		0.44	ASTM D5470
Viscosity (Pa·s@25°C)		200~400	ASTM D2196 Brookfield Viscometer, #7 spindle@10rpm
Density(g/cm ³)		3.1	ASTM D792
Hardness (Shore00)		50	ASTM D2240
Minimum BLT (μm)		100	HON Internal
Working Time@25°C (h)		2.0	HON Internal
Curing Time	@25°C (h)	18.0	HON Internal
	@120°C (h)	0.5	HON Internal
Dielectric Strength (KV/mm)		10	ASTM D149
Volume Resistivity (ohm-cm)		1.0×10^{13}	ASTM D257
Flammability Rating		V-0(Equivalent)	UL 94
Operating Temperature (°C)		-40~150	HON Internal

*Typical property data values should not be used as specifications

Honeywell Electronic Materials

USA: 1-509-252-2102
 China: 400-840-2233
 Germany: 49-5137-999-9199
 Japan: 81-3-6730-7092
 Korea: 82-2-3483-5076
 Singapore: 65-6580-3593

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